


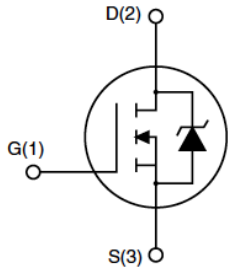


## Description

<h3>Features</h3> <ul style="list-style-type: none"><li>● 600V,20A</li><li>● <math>R_{DS(ON)} = 0.3\Omega</math> (Typ.) @ <math>V_{GS} = 10V</math>, <math>I_D = 10A</math></li><li>● Fast Switching</li><li>● Improved dv/dt Capability</li><li>● 100% Avalanche Tested</li></ul>	<h3>Application</h3> <ul style="list-style-type: none"><li>● Switch Mode Power Supply(SMPS)</li><li>● Uninterruptible Power Supply(UPS)</li><li>● Power Factor Correction (PFC)</li></ul>		
 <p>TO-220F</p>	 <p>TO-3P</p>	 <p>TO-247</p>	 <p>Schematic Diagram</p>

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.		Units
			TO-3P/TO-247	TO-220F	
V <sub>DSS</sub>	Drain-Source Voltage		600		V
V <sub>GSS</sub>	Gate-Source Voltage		±30		V
I <sub>D</sub>	Continuous Drain Current	T <sub>C</sub> = 25°C	20		A
		T <sub>C</sub> = 100°C	13		A
I <sub>DM</sub>	Pulsed Drain Current <sup>note1</sup>		80		A
E <sub>AS</sub>	Single Pulsed Avalanche Energy <sup>note2</sup>		1350		mJ
P <sub>D</sub>	Power Dissipation	T <sub>C</sub> = 25°C	416	167	W
R <sub>θJC</sub>	Thermal Resistance, Junction to Case		0.3	0.75	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient		60	90	°C/W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150		°C

**Electrical Characteristics** ( $T_C=25^{\circ}\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	600	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 25℃	-	-	1	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±30V	-	-	±100	nA
On Characteristics						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250μA	2	3	4	V
R <sub>DS(on)</sub>	Static Drain-Source on-Resistance note3	V <sub>GS</sub> =10V, I <sub>D</sub> =10A	-	0.3	0.45	Ω
Dynamic Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1.0MHz	-	2980	-	pF
C <sub>Oss</sub>	Output Capacitance		-	291	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	40	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DD</sub> = 480V, I <sub>D</sub> = 20A, V <sub>GS</sub> = 10V	-	80	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	12	-	nC
Q <sub>gd</sub>	Gate-Drain(“Miller”) Charge		-	34	-	nC
Switching Characteristics						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> = 250V, I <sub>D</sub> =20A, R <sub>G</sub> = 25Ω	-	37	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	66	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	175	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	84	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	20	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	80	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>SD</sub> = 20A	-	-	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> =0V, I <sub>S</sub> =20A,	-	450	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	di/dt=100A/μs	-	7.1	-	μC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2.  $I_{AS} = 16A, V_{DD} = 50V, R_G = 25\Omega$ , Starting  $T_J = 25^{\circ}\text{C}$ 

3. Pulse Test: Pulse Width $\leq 300\mu s$ , Duty Cycle $\leq 1\%$

## Typical Performance Characteristics

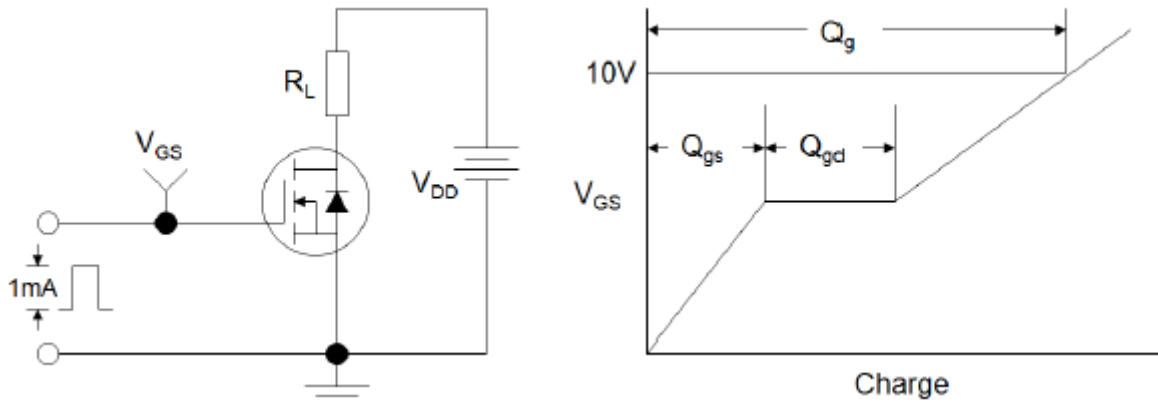


Figure1:Gate Charge Test Circuit & Waveform

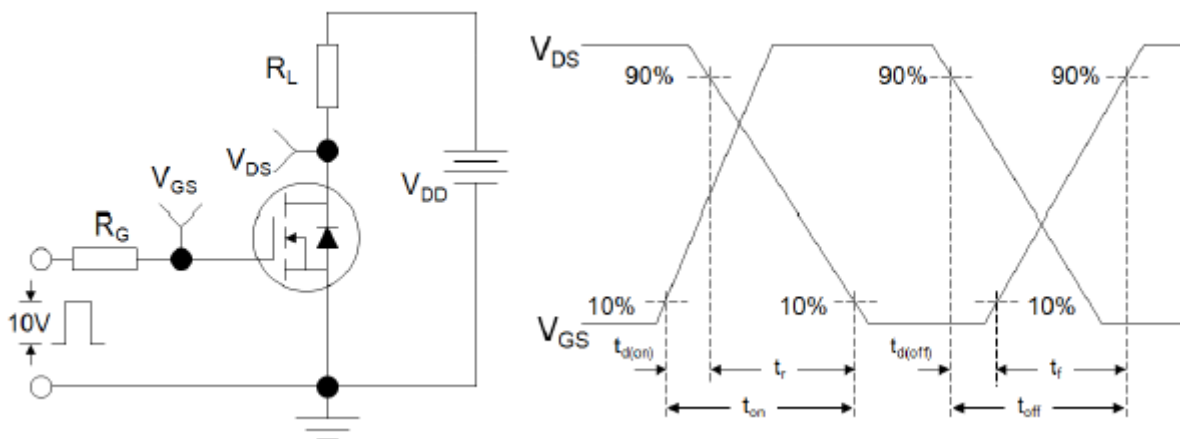


Figure 2: Resistive Switching Test Circuit & Waveforms

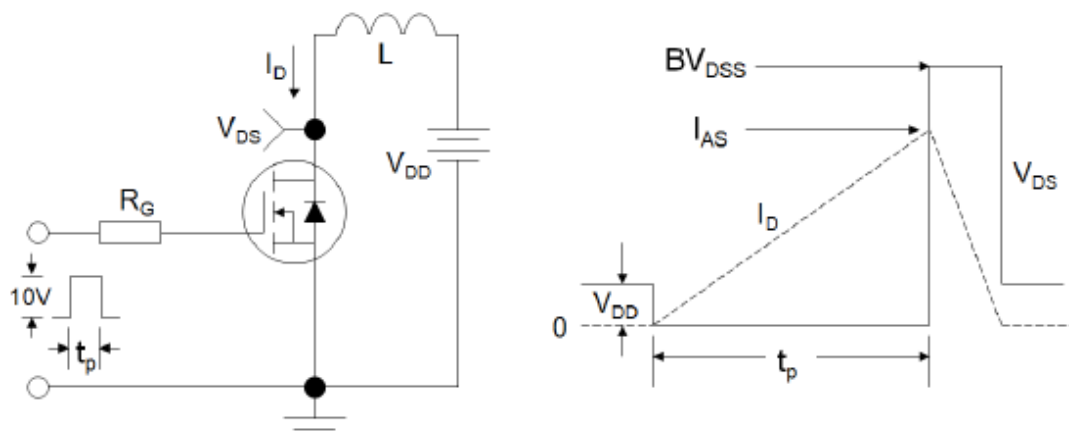
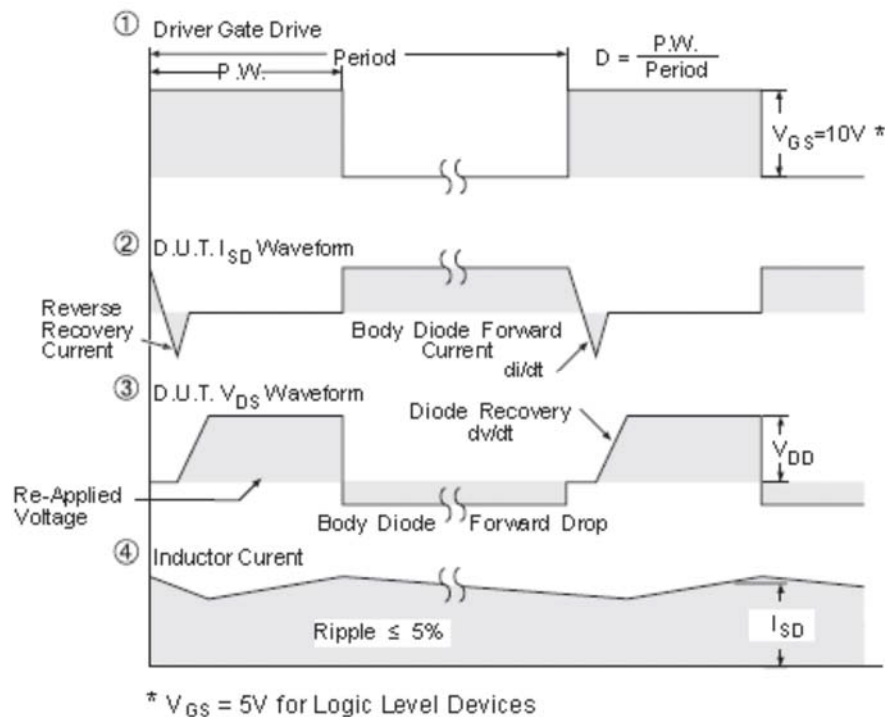
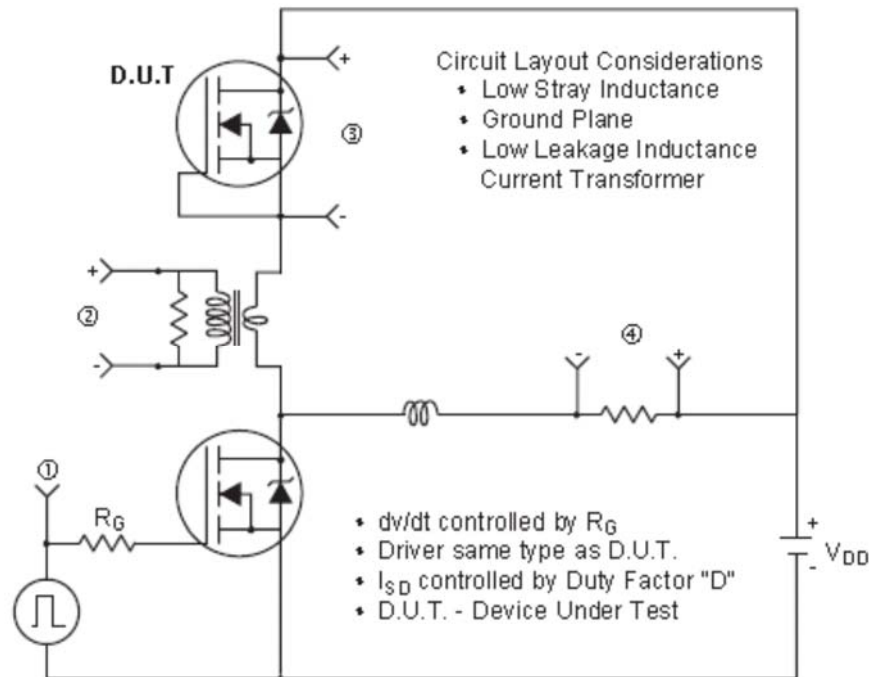


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms



**Figure 4: Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms (For N-channel)**